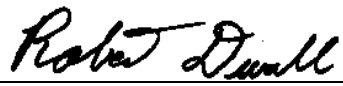


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## **1. INTRODUCTORY DESCRIPTION**

- A. This procedure establishes the methods for testing a .IC3650SPFA Power Factor Card.
- B. Environmental ranges: 70 +/- 10 Deg. F. with 20-75% R.H.
- C. Unit warm-up/stabilization period requirement: NONE
- D. Personnel using this procedure are expected to have a high degree of confidence and expertise in related testing and calibration procedures.
- E. Procedures not explained here are considered to be understood as common practice.

## **2. TEST EQUIPMENT VERIFICATION**

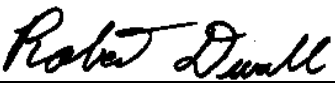
- A. Verify the accuracy of the standard(s) used in the repair/calibration process by evidence of recent calibration labeling affixed to the test equipment.
- B. All measurement standards used in this procedure shall be traceable to the NATIONAL INSTITUTE of STANDARDS and TECHNOLOGY (N.I.S.T.) and shall have the accuracy, stability, range and resolution required for the intended use.
- C. Unless otherwise specified, the collective uncertainty of the Measurement Standard(s) shall not exceed twenty five percent of the acceptable tolerance for each characteristic being calibrated.
- D. All deviations shall be documented.

## **3. EQUIPMENT CLEANING**

- A. All equipment cleaning will be performed as instructed in the GEES SOP Sec. 14.0

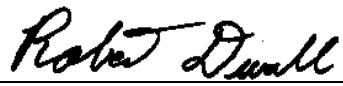
## **4. EQUIPMENT INSPECTION**

- A. The following criteria should be used as a guideline or basis for the inspection process of the this unit:
  - 1. Wires broken or cracked.
  - 2. Terminal strips / connectors broken or cracked.
  - 3. Loose wires.
  - 4. Components visually damaged.
  - 5. Capacitors leaking.
  - 6. Solder joint, cold.
  - 7. Circuit board discolored or burned.
  - 8. Printed wire runs burned or damaged.

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## 5. REVISION HISTORY

Revision	Date	Initials	Reason for Revision
A	09/29/94	PDK	Initial Procedure – After Verification
B	06/07/02	RKD	Added section 5 & 6, Changed procedure number
C			
D			
E			
F			
G			
H			
I			
J			
K			

<b>g</b> <b>GE Industrial Systems</b>	<b>TEST and OPERATING PROCEDURE</b>	
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## 6. REFERENCE DOCUMENTATION

- Reference: GEK
- Factory Procedure #

## 7. THEORY OF OPERATION

- A. Refer to the IC3650SPFA Module information Bulletin(s) for theory of operation.

## 8. TEST EQUIPMENT TO BE USED

- General Purpose Testing Computer with data acquisition cards.
- General Purpose Testing Interface
- General Purpose Testing Interface Auxiliary connector assembly
- Personality Module # 20
- DC power supply set for +27

## 9. FINAL TEST AND OPERATION PROCESS

- Assure that the GPTC and GPTI are connected and operational.
- Connect the GPTI Aux. connector assembly to the GPTI
- Connect the +27 volt supply to the Aux. connector assembly.
- Power up the computer and select board testing programs from the menu.
- Follow the instructions on the screen for testing of the card.

## 10. SPECIAL INFORMATION

**TEST WRITTEN BY:** Paul Kelley

**DATE:** 09/29/94